

FP1006

High frequency, high current power inductors



Product features

- 10.2 x 8.0 x 6.0mm surface mount package
- Ferrite core material
- High current carrying capacity, Low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 85nH to 220nH
- Current range from 38 to 100 amps
- Frequency range up to 2MHz

Applications

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Point-of-load modules
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- Graphics cards and battery power systems
- DCR sensing

Environmental data

- Storage temperature range (component):
-40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C
(ambient plus self-temperature rise)
- Solder reflow temperature:
J-STD-020 (latest revision) compliant



Product Specifications							
Part Number	OCL ¹ ± 10% (nH)	FLL ² Min. (nH)	I _{rms} ³ (Amps)	I _{sat} ¹ @ 25°C (Amps)	I _{sat} ² @ 125°C (Amps)	DCR (mΩ) @ 20°C	K-factor ⁴
R1 Version							
FP1006R1-R08-R	85	61	53	100	70	0.27 ± 12%	454
FP1006R1-R10-R	100	72		85	64		454
FP1006R1-R12-R	120	86		71	53		454
FP1006R1-R16-R	160	115		55	40		454
FP1006R1-R22-R	220	158		38	28		454
R2 Version							
FP1006R2-R08-R	85	61	45	100	70	0.36 ± 8.6%	454
FP1006R2-R10-R	100	72		85	64		454
FP1006R2-R12-R	120	86		71	53		454
FP1006R2-R16-R	160	115		55	40		454
FP1006R2-R22-R	220	158		38	28		454

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V_{rms}, 0.0A_{dc}

2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V_{rms}, I_{sat}¹

3 I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

4 I_{sat}¹: Peak current for approximately 20% rolloff at +25°C.

5 I_{sat}²: Peak current for approximately 20% rolloff at +125°C.

6 K-factor: Used to determine B_{p-p} for core loss (see graph). B_{p-p} = K * L * ΔI * 10⁻³, B_{p-p}: (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).

7 Part Number Definition: FP1006Rx-Rxx-R

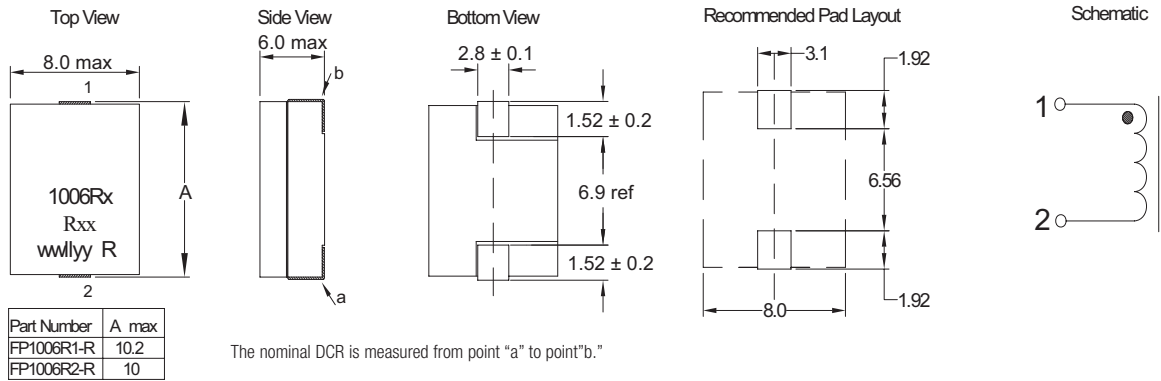
• FP1006 = Product code and size

• Rxx = Inductance value in μH, R = decimal point

• Rx is the DCR indicator

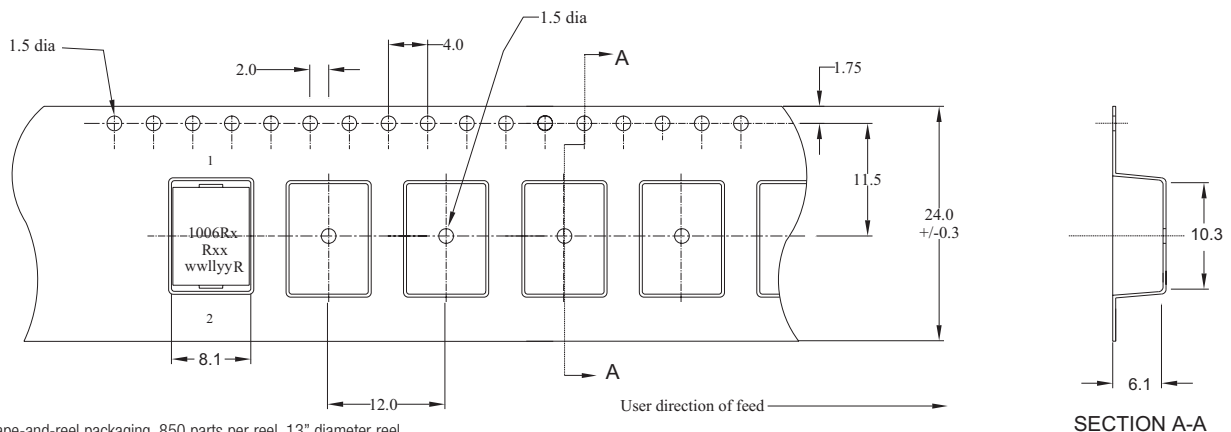
• "-R" suffix = RoHS compliant

Dimensions- mm



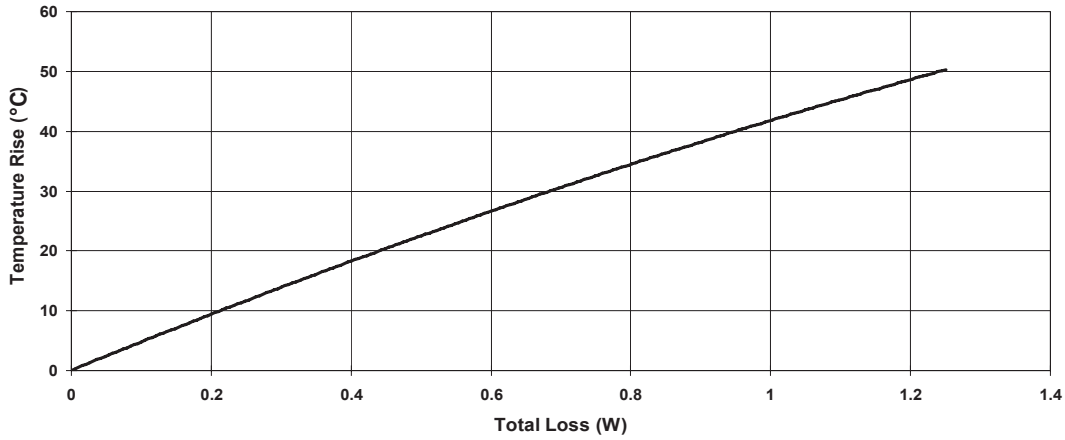
Part Marking: 1006Rx (Rx = DCR Indicator) Rxx = Inductance value in μH. (R = Decimal point) wwlyy = Date code R = Revision level

Packaging information - mm

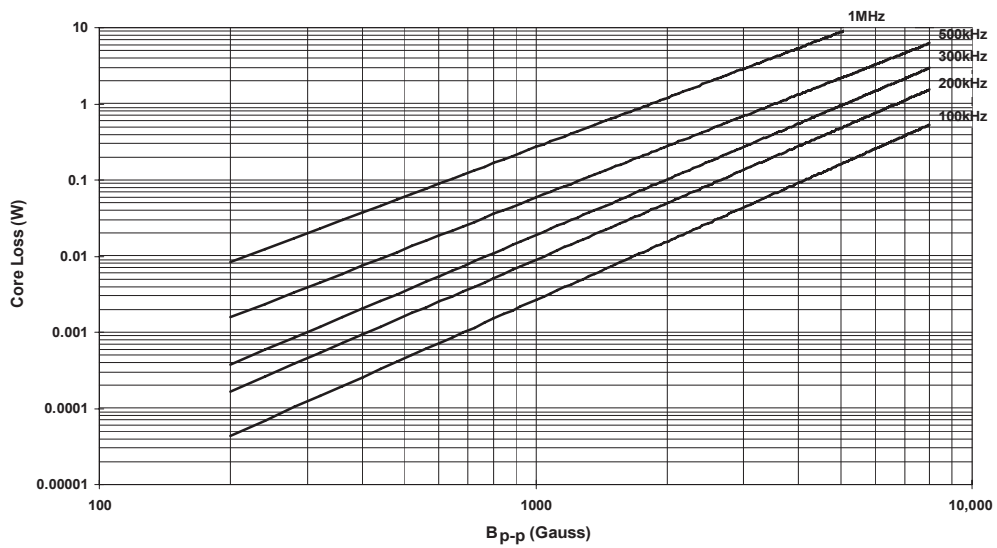


Supplied in tape-and-reel packaging, 850 parts per reel, 13" diameter reel.

Temperature rise vs total loss

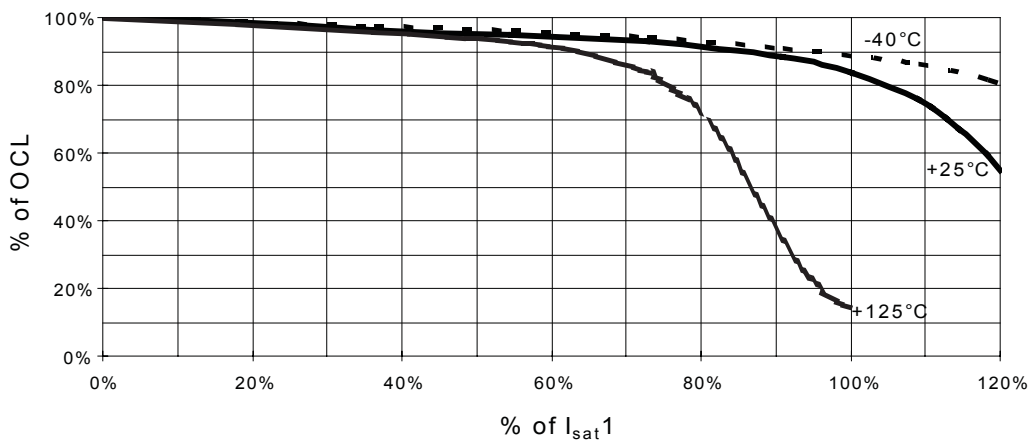


Core loss vs Bp-p



Inductance characteristics

% of OCL vs. % of $I_{sat 1}$



Solder Reflow Profile

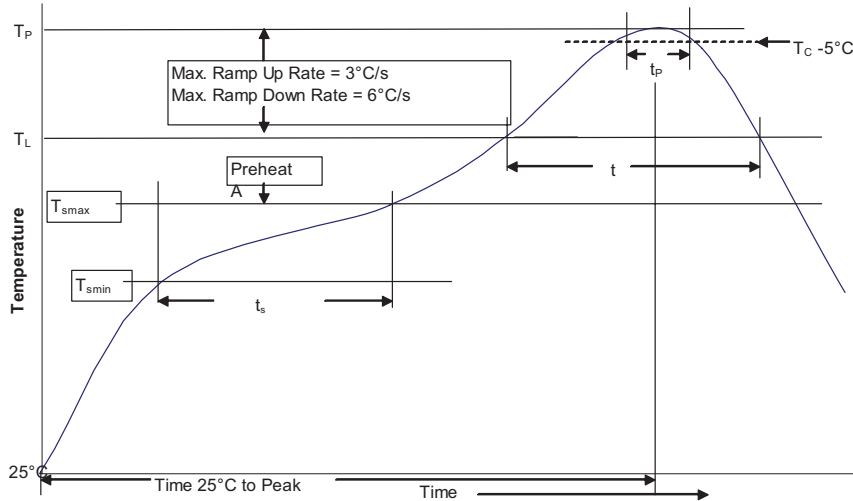


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume <350 mm ³	Volume ≥ 350 mm ³
<2.5 mm	235°C	220°C
≥ 2.5 mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume <350 mm ³	Volume $350 - 2000$ mm ³	Volume >2000 mm ³
<1.6 mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5 mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C
	• Temperature max. (T_{smax})	150°C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds
Average ramp up rate T_{smax} to T_P	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_P to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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